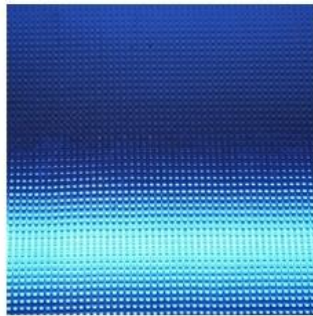




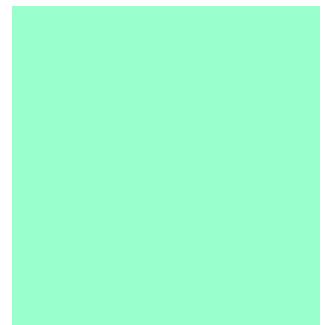
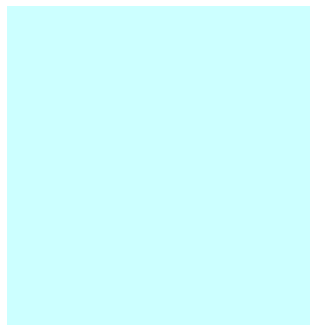
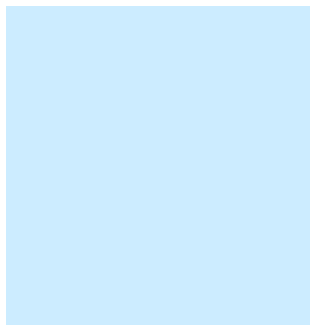
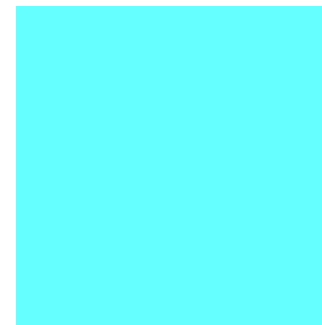
Vertically Integrated Systems

Product Catalog



2011

Ultrahigh-Speed Components



Issue 101209-02 Apr 2011

www.v-i-systems.com

VI Systems GmbH Hardenbergstrasse 7 D-10623 Berlin



Table of Content

Introduction	4
Fabless Company Concept	5
Technology Description	6
Optical Subassemblies for 25 Gbit/s and 40 Gbit/s	
28 Gbit/s Optical Subassembly (TOSA/ROSA)	7
40 Gbit/s Optical Subassembly (TOSA/ROSA)	7
Fiber Coupled Test Modules for up to 40 Gbit/s	
Transmitter module	8
Photodetector module	8
Chip on RF-Mount Test Devices	9
Ceramic Testboards for up to 40 Gbit/s	
Transmitter test boards (VCSEL /driver)	10
Receiver test boards (PIN PD / TIA)	10
High Speed ICs for 28Gbit/s and 40 Gbit/s	
28 /40 Gbit/s Transimpedance Amplifier (TIA)	11
28 /40 Gbit/s VCSEL driver	12
VCSELs and Photodetectors for 25 Gbit/s and 40 Gbit/s	
850nm single VCSEL	13
850nm VCSEL arrays	13
700-890nm single PIN PD	14
700-890nm PIN PD arrays	14



Vertically Integrated Systems

Company Introduction

Systems GmbH (VIS), founded in 2006, is a fabless developer and producer of ultrafast cost-effective optoelectronic devices, that will replace the present generation of devices in short and medium-distance optical communication interconnects.

VI Systems GmbH offers optical subassemblies and fiber coupled modules for applications in optical data communications and related consumer markets. In contrast to current optical- and electrical-based technologies, the optical solutions based on VIS components and systems will overcome the rising technological barriers created by the market driven continual increase in optical data transmission rates. With VIS proprietary solutions, telecom and computer equipment manufacturers as well as telecom service providers will be able to meet the continuously growing performance requirements of the future.

Based on the Company's advanced proprietary technology, innovative design concepts, and technical expertise, VIS devices offer a unique combination of high speed, low power consumption, reliability, and low cost.

VI Systems' uniqueness is based on its revolutionary concept of vertically-integrated modulator systems a new concept in ultrahigh-speed optical signal transmission and the integration into a low cost fiber optics components.

The company offers a range a optical components, integrated circuits and highly optimized packaging solutions.

Fabless Factory

VI Systems designs and manufactures their products with the leading foundries in the world. Therefore the reliability of the process and the scalability is ensured from the very early stage of the development.

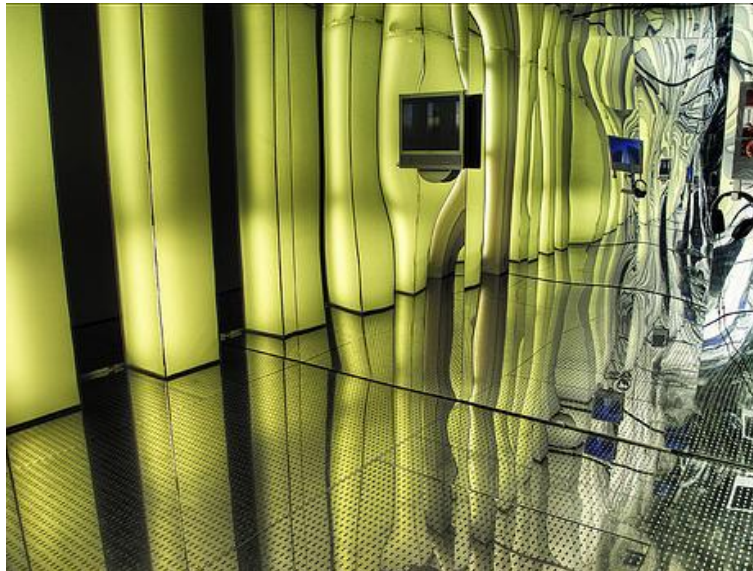


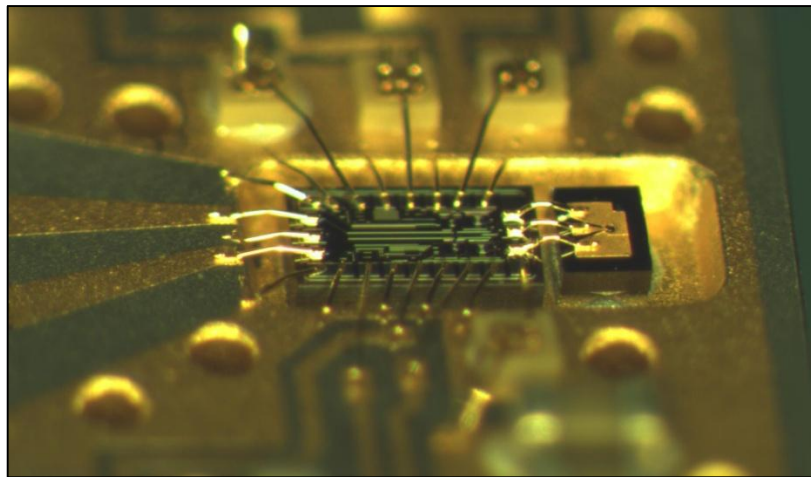
Image by JeffreySG

VI Systems concentrates on the design and qualification of ultrahigh-speed components. The manufacturing of optical components, integrated circuits and optical packaging is outsourced to foundries and electronics manufacturing service companies. Our optical components and integrated products are sold to major manufacturing companies, who then use these components to produce high speed optical modules which are the basis of virtually all ultra high speed optical data transmitting systems.

VI Systems leads a trend in the fiber optic communications industry where manufacturers increasingly seek to outsource production to specialist foundries in order to reduce overall costs and accelerate time to market.

Integrated Optical Solutions

A novel concept of integrated ultrahigh-speed components is introduced by VI Systems. State-of-the-art SiGe BICMOS integrated circuits are customized to match the performance of ultrahigh-speed optical VCSEL transmitter and PIN receiver components. Both key elements are assembled in a proprietary high frequency design to delivery outstanding performance over a wide temperature range .

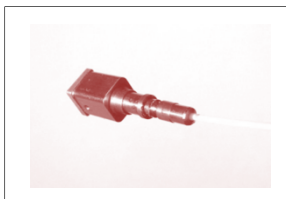


40 Gbit/s receiver microassembly

VI Systems offers a range of subcomponents for the use in short reach optical interconnects. The optical engines offer a unique combination of high speed, low power consumption, small footprint (TO can), high reliability and low cost. VI Systems' unique selling point is based on a combination of its revolutionary concept of ultra-high frequency small footprint micro-assembly integration of advanced electro-optic components, development of advanced high speed ICs and development of modulation approaches.

Optical Subassemblies (OSA)

T25-850 Ultrahigh-Speed TOSA
Transmitter subassembly (up to 28 Gbit/s)



Parameter	Typical
Emitting Wavelength	850 nm
Data rate	28 Gbit/s
Power dissipation	< 300 mW

T40-850 Ultrahigh-Speed TOSA
Transmitter subassembly (up to 40 Gbit/s)



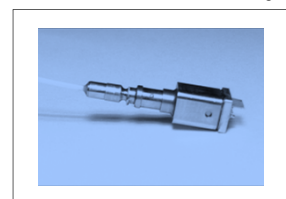
Parameter	Typical
Emitting Wavelength	850 nm
Data rate	40 Gbit/s
Power dissipation	< 300 mW

D25-850 Ultrahigh-Speed ROSA
Receiver subassembly (up to 28 Gbit/s)



Parameter	Typical
Operating Wavelength	700-890 nm
Bandwidth	> 25 GHz
Fiber Type	50/125 μ m

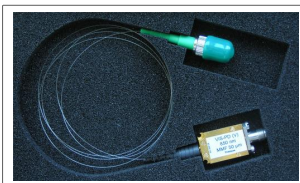
D40-850 Ultrahigh-Speed ROSA
Receiver subassembly (up to 40 Gbit/s)



Parameter	Typical
Operating Wavelength	700-890 nm
Bandwidth	> 35 GHz
Fiber Type	50/125 μ m

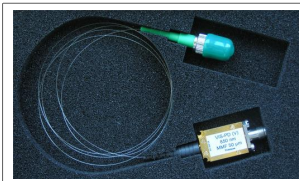
Fiber Coupled Modules for High Speed Tests

V25-850 Multi Mode Fiber Coupled VCSEL Transmitter Module (up to 28 Gbit/s)



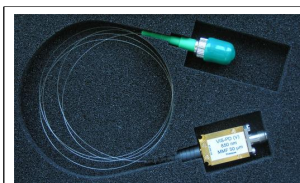
Parameter	Typical
Emission Wavelength	850 nm
Peak Output Power	3 mW
Fiber Type	50/125 μm

V40-850 Multi Mode Fiber Coupled VCSEL Transmitter Module (up to 40 Gbit/s)



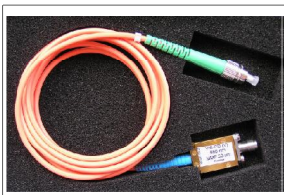
Parameter	Typical
Emission Wavelength	850 nm
Peak Output Power	3 mW
Fiber Type	50/125 μm

V40-850 Multi Mode Fiber Coupled VCSEL Transmitter Module (up to 40 Gbit/s)



Parameter	Typical
Emission Wavelength (single mode)	850 nm
Peak Output Power	1 mW
Fiber Type	50/125 μm

D30-850M Multi Mode Fiber Coupled PIN Photodetector Module (up to 40 Gbit/s)



Parameter	Typical
Operating Wavelength	700-890 nm
3dB Bandwidth	> 30 GHz
Fiber Type	50/125 μm

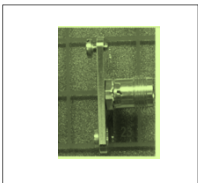
Chip on RF-Mount

VCSEL chip on holder (up to 40 Gbit/s)
V40-850H



Parameter	Typical
Differential electrical gain	3.0 k Ω
Bandwidth	35 GHz
Power dissipation	145 mW

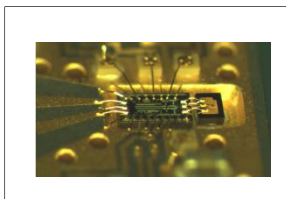
Photo detector chip on holder (35GHz)
D30-850H



Parameter	Typical
Differential electrical gain	3.0 k Ω
Bandwidth	35 GHz
Power dissipation	145 mW

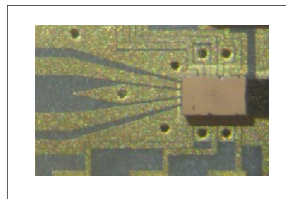
Ultrahigh-Speed Testboards

T40-850TB-WB 40Gbit/s transmitter
Testboard subassembly (wire bond)



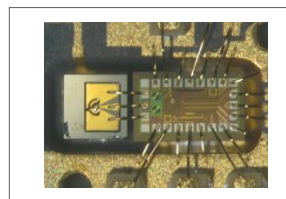
Parameter	Typical
Emitting Wavelength	850 nm
Rise/Fall Time	< 10 ps
Power dissipation	< 300 mW

T40-850TB-FC 40 Gbit/s transmitter
Testboard subassembly (flip-chip)



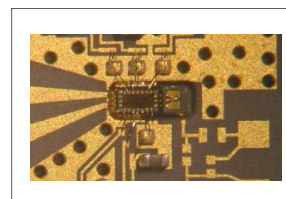
Parameter	Typical
Emitting Wavelength	850 nm
Rise/Fall Time	< 10 ps
Power dissipation	< 300 mW

R40-850TB-WB 40 Gbit/s receiver
Testboard subassembly (wire bond)



Parameter	Typical
Operating Wavelength	700-890 nm
Bandwidth	> 35 GHz
Fiber Type	50/125 μ m

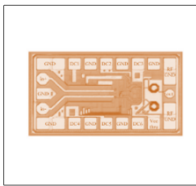
R40-850TB-FC 40 Gbit/s receiver
Testboard subassembly (flip-chip)



Parameter	Typical
Operating Wavelength	700-890 nm
Bandwidth	> 35 GHz
Fiber Type	50/125 μ m

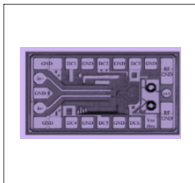
VCSEL Driver ICs

High Speed VCSEL driver IC (up to 28Gbit/s)
A25-120C80



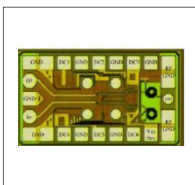
Parameter	Typical
Data rate	up to 28 Gbit/s
Supply voltage	3.3 V
Power dissipation	120mW

High Speed DM VCSEL driver chip (up to 40Gbit/s)
A40-150C80



Parameter	Typical
Data rate	up to 40 Gbit/s
Supply voltage	3.3 V
Power dissipation	150 mW

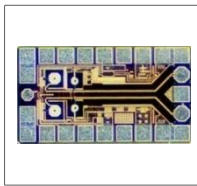
High Speed modulator driver chip (up to 40Gbit/s)
A40-300C90



Parameter	Typical
Data rate	up to 40 Gbit/s
Supply voltage	5 V
Power dissipation	370mW

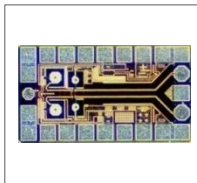
Transimpedance Amplifier (TIA)

High Speed TIA chip (up to 28 Gbit/s)
A25-120C80



Parameter	Typical
Differential electrical gain	3.0 k Ω
Bandwidth	25 GHz
Power dissipation	120 mW

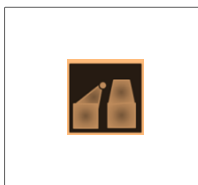
High Speed TIA chip (up to 40 Gbit/s)
A40-150C80



Parameter	Typical
Differential electrical gain	3.0 k Ω
Bandwidth	35 GHz
Power dissipation	150 mW

850nm VCSELs - Vertical Cavity Surface Emitting Lasers

High Speed VCSEL Chip (16 Gbit/s)
V15-850C



Parameter	Typical
Emission Wavelength	850 nm
Peak Output Power	6 mW
Rise Time (20% to 80%)	< 15 ps

Ultrahigh-Speed VCSEL Chip (28 Gbit/s)
V25-850C



Parameter	Typical
Emission Wavelength	850 nm
Peak Output Power	6 mW
Rise Time (20% to 80%)	< 15ps

High Speed VCSEL Chip (40 Gbit/s)
V40-850C



Parameter	Typical
Emission Wavelength	850 nm
Peak Output Power	6 mW
No. of single chips	4 or 12

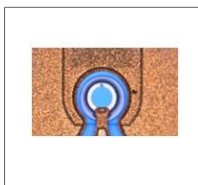
Ultrahigh-Speed VCSEL Array (28 Gbit/s)
V25-850C4 / V25-850C12



Parameter	Typical
Emission Wavelength	850 nm
Peak Output Power	6mW
No. of single chips	4 or 12

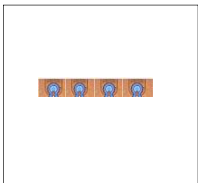
850nm Photodetector PIN Diode

High Speed Photodetector (up to 40 Gbit/s)
D30-850C



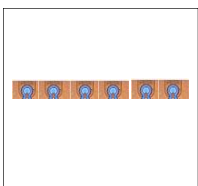
Parameter	Typical
Operating Wavelength	700-890 nm
3 dB Bandwidth	~ 30 GHz
Rise Time (20% to 80%)	6 ps

High Speed Photodetector (up to 40 Gbit/s)
D30-850C4



Parameter	Typical
Operating Wavelength	850 nm
3 dB Bandwidth	> 30 GHz
No. of single PDs	4

High Speed Photodetector (up to 40 Gbit/s)
D30-850C12



Parameter	Typical
Operating Wavelength	850 nm
3 dB Bandwidth	> 30 GHz
No. of single PDs	12



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All product specifications and descriptions are subject to change without notice.
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